EVG Technology Day

in HSINCHU, Taiwan
November 20, 2019

Schedule

Wednesday, Nov. 20, 2019
08:00 - 16:00 hrs
EVG Technology Day

Location

Hsinchu Ambassador Hotel
188 Chung Hwa Road Section 2

EVG Speaker

Paul Lindner
Executive Technology Director

Frank Bögelsack
Product Manager

Christine Thanner
Technology Development

Cindy Lee
Technology Development & IP Manager Taiwan

Guest Speaker

OKMETIC

In cooperation with

Register

For more information and to register for free:

www.EVGroup.com/events

Artificial Intelligence and Augmented Reality: Need for Innovative Manufacturing Solutions

Agenda

08:00	**Registration - Our Experts Will Be Available for a Coffee and Chat!**
09:00	**Keynote: Yole Développement**
Lithography Trends for Advanced Packaging	
09:30	Applications & Trends in Advanced Packaging
09:35	Status and Technology Update Temporary Bonding
10:05	Technology Announcement: EVG Maskless Exposure
10:35	**Coffee Break**
3D Integration and Heterogeneous Integration	
10:55	Applications & Trends in 3D and Heterogeneous Integration
11:00	Hybrid Bonding for Die Partitioning and Memory Integration
11:30	Next Generation Devices Scaling and Backside Power Distribution Enabled by Bondscale™
11:40	Metrology Needs for Heterogeneous Integration
11:55	**Invited Lunch**
NILPhotonics® for 3D Sensing and Augmented Reality	
13:10	Trends & Recent Developments in Photonics and Micro Optics
13:15	SmartNIL® Nanoimprint Lithography - Transition to 300 mm Volume Manufacturing
13:45	Lens Molding and Stacking for Advanced Sensing
14:00	**Coffee Break**
MEMS, RF and Power Devices: Autonomous Driving and E-Mobility	
14:15	**Keynote: ST Microelectronics** **ST Imaging Products Leveraging on Taiwan Semiconductor Ecosystem**
14:40	**Okmetic - Okmetic Engineered Substrates for MEMS and RF**
15:05	Wafer Bonding for High Volume Manufacturing
15:25	EVG ComBond®: High Vacuum Encapsulation
15:45	**Lucky Draw & Closing Remarks**